Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	2439	cover$3 near20 (desicc$3 moisture) and (light-emitting light adj emitting laser photodiode photodetector photodetecting CMOS adj imag$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 12:57
L3	491	cover$3 near20 (desicc$3 moisture) near20 seal$3 and (light-emitting light adj emitting laser photodiode photodetector photodetecting CMOS adj imag$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 12:57
L4	74	cover$3 near20 (desicc$3 moisture) near20 seal$3 near20 resin and (light-emitting light adj emitting laser photodiode photodetector photodetecting CMOS adj imag$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 13:54
L5	105	cover$3 near20 (desicc$3 moisture) near20 seal$3 near20 (epoxy resin thermoplastic thermosetting polyethylene terephtthalate polypropylene polystyrene acrylic polyphenylene adj ether polyamide polycarbonate polyacetal polybutylene polyphenylene adj sulfide polyether adj ether adj ketone liquid adj crystal adj polymer fluororesin polyurethane adj resin elastomer urea phenol melamine furan alkyd polyester diallyl adj phthatale silicon adj resin polyurethane) and (light-emitting light adj emitting laser photodiode photodetector photodetecting CMOS adj imag$3 charge adj couple$1 charge-couple$1 CCD CID)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 16:36
L6	22	5 and cover$3 near6 (side sides side adj surface)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 13:27
L7	22	5 and cover$3 near6 (side sides side adj surface) and (resin epoxy seal$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 13:29

L8	13	5 and cover$3 near12 (side sides side adj surface) near12 (resin epoxy seal$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 13:29
L9	2	jp-11277089$-$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 14:50
L10	2	jp-11277090$-$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 14:50
L11	1	"11-277090"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 15:11
L12	2	jp-2000173766$-$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 15:11
L14	2	"6621143"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/07 16:12
L15	2	("6621143").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/07 16:13
L16	4	EP38 near4 resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 16:59
L17	0	bump adj electrode near6 counter adj electrode and (light-emitting light adj emitting laser).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 16:59
L18	2	bump near6 counter adj electrode and (light-emitting light adj emitting laser).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 17:09

L19	2282	bump.ti,ab,clm. and (light-emitting light adj emitting laser).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 17:10
L20	3	bump.ti,ab,clm. and (light-emitting light adj emitting laser).ti,ab,clm. and bump near4 (counter adj electrode)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 17:11
L21	341	stud adj bump near4 (technique method)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 17:12
L22	74	stud adj bump near4 (technique method).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 17:12
L26	6538	((257/81) or (257/99) or (257/100) or (257/428) or (257/431) or (257/432) or (257/433)).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/07 19:27
L27	146	26 and (moisture desiccant) and seal$3 and transparent near4 (substrate cover)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 18:18
L28	360	26 and seal$3 and transparent near4 (substrate cover)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 18:18
L29	214	28 not 27	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/07 18:38
L30	2	("20010018236").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/07 18:52
L31	0	("su-8adjphotoresistnear6transparent").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/07 18:52

L32	3	su-8 adj photoresist near6 transparent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/07 18:53
S1	7	"812454".ap.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/06 19:22
S2	1	(US-20040245530-$).did.	US-PGPUB	OR	OFF	2005/08/06 19:22
S3	0	2001-339151$-$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/06 19:23
S4	2	jp-2001339151$-$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/06 19:24
S5	157476	(light adj emitting light-emitting laser opto-electronic optoelectronic photo adj diode photodetector photodiode CCD CMOS adj imag$3) and (desiccant water)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/06 20:15
S6	245	(257/682).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/06 20:07
S7	22	S5 and S6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/06 20:07
S8	38805	(light adj emitting light-emitting laser opto-electronic optoelectronic photo adj diode photodetector photodiode CCD CMOS adj imag$3) and (desiccant moisture)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/06 20:16
S9	7096	(light adj emitting light-emitting laser opto-electronic optoelectronic photo adj diode photodetector photodiode CCD CMOS adj imag$3) and (desiccant moisture damage near3 water).ti, ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/06 20:16

| S10 | 2 | S6 and S9 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/06 20:16 |